

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

APPLICANT:	C. Huang	CONF. NO.:	7288
U.S. SERIAL NO.:	10/696,198	EXAMINER:	H. Trinh
FILED:	October 28, 2003	GROUP:	2814
FOR:	MULTI-CHIP PACKAGE DEVICE WITH HEAT SINK AND FABRICATION METHOD THEREOF		

Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

Sir/Madam:

AMENDMENT

Applicant is in receipt of the Office Action dated May 23, 2008 of the above-referenced application. Please amend the application as follows:

Amendments to the claims are reflected in the listing of claims which begins on page 2 of this paper.

Remarks begin on page 4 of this paper.